

# FDC6310P

## Dual P-Channel 2.5V Specified PowerTrench<sup>®</sup> MOSFET

### General Description

These P-Channel 2.5V specified MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

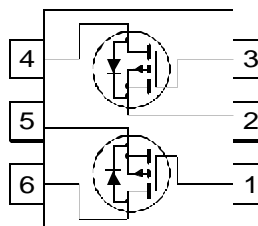
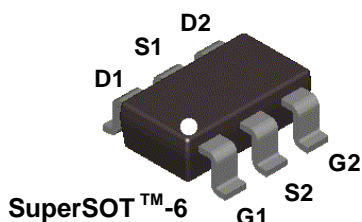
These devices have been designed to offer exceptional power dissipation in a very small footprint for applications where the bigger more expensive SO-8 and TSSOP-8 packages are impractical.

### Applications

- Load switch
- Battery protection
- Power management

### Features

- -2.2 A, -20 V.  $R_{DS(ON)} = 125\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$   
 $R_{DS(ON)} = 190\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$
- Low gate charge
- Fast switching speed
- High performance trench technology for extremely low  $R_{DS(ON)}$
- SuperSOT™ -6 package: small footprint 72% smaller than standard SO-8); low profile (1mm thick)



### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage	-20	V
V <sub>GSS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub>	Drain Current – Continuous (Note 1a)	-2.2	A
		-6	
P <sub>D</sub>	Power Dissipation for Single Operation (Note 1a)	0.96	W
		0.9 (Note 1b)	
		0.7 (Note 1c)	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics

R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient (Note 1a)	130	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case (Note 1)	60	°C/W

### Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.310	FDC6310P	7"	8mm	3000 units

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_b = -250\ \mu\text{A}$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_b = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		-11		mV/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
$I_{GSSF}$	Gate–Body Leakage, Forward	$V_{GS} = 12\text{ V}, V_{DS} = 0\text{ V}$			100	nA
$I_{GSSR}$	Gate–Body Leakage, Reverse	$V_{GS} = -12\text{ V}, V_{DS} = 0\text{ V}$			-100	nA

### On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_b = -250\ \mu\text{A}$	-0.6	-1.0	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_b = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		3		mV/°C
$R_{D(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -4.5\text{ V}, I_b = -2.2\text{ A}$ $V_{GS} = -2.5\text{ V}, I_b = -1.8\text{ A}$ $V_{GS} = -4.5\text{ V}, I_b = -2.2\text{ A}, T_J = 125^\circ\text{C}$		100 145 137	125 190 184	m $\Omega$
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -4.5\text{ V}, V_{DS} = -5\text{ V}$	-6			A
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{ V}, I_b = -3.5\text{ A}$		6		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		337		pF
$C_{oss}$	Output Capacitance			88		pF
$C_{rss}$	Reverse Transfer Capacitance			51		pF

### Switching Characteristics (Note 2)

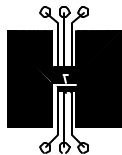
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = -10\text{ V}, I_b = -1\text{ A},$ $V_{GS} = -4.5\text{ V}, R_{GEN} = 6\ \Omega$		9	18	ns
$t_r$	Turn–On Rise Time			12	22	ns
$t_{d(off)}$	Turn–Off Delay Time			10	20	ns
$t_f$	Turn–Off Fall Time			5	10	ns
$Q_g$	Total Gate Charge	$V_{DS} = -10\text{ V}, I_b = -2.2\text{ A},$ $V_{GS} = -4.5\text{ V}$		3.7	5.2	nC
$Q_{gs}$	Gate–Source Charge			0.65		nC
$Q_{gd}$	Gate–Drain Charge			1.3		nC

### Drain–Source Diode Characteristics and Maximum Ratings

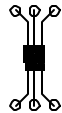
$I_S$	Maximum Continuous Drain–Source Diode Forward Current			-0.8		A
$V_{SD}$	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -0.8\text{ A}$ (Note 2)		0.77	-1.2	V

#### Notes:

- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a)  $130^\circ\text{C/W}$  when mounted on a  $0.125\text{ in}^2$  pad of 2 oz. copper.



b)  $140^\circ\text{C/W}$  when mounted on a  $0.004\text{ in}^2$  pad of 2 oz. copper



c)  $180^\circ\text{C/W}$  when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width <  $300\ \mu\text{s}$ , Duty Cycle < 2.0%

### Typical Characteristics

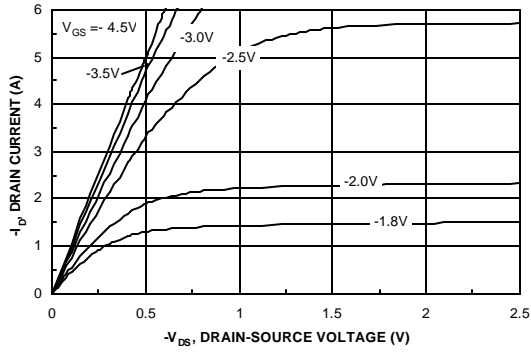


Figure 1. On-Region Characteristics.

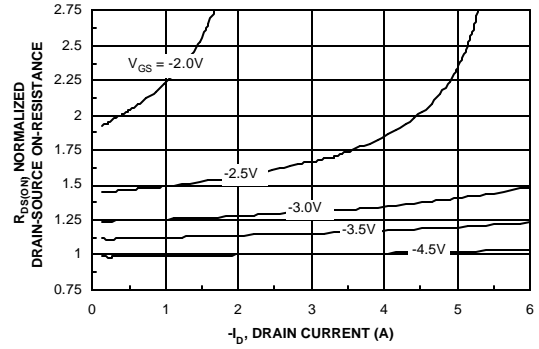


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

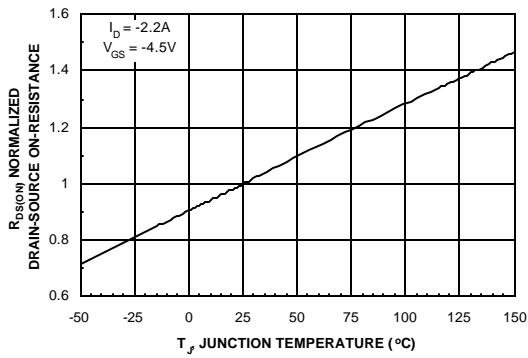


Figure 3. On-Resistance Variation with Temperature.

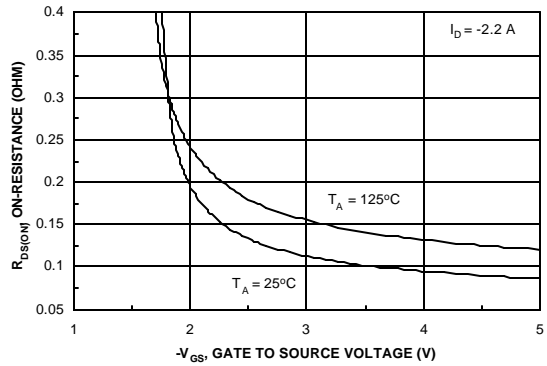


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

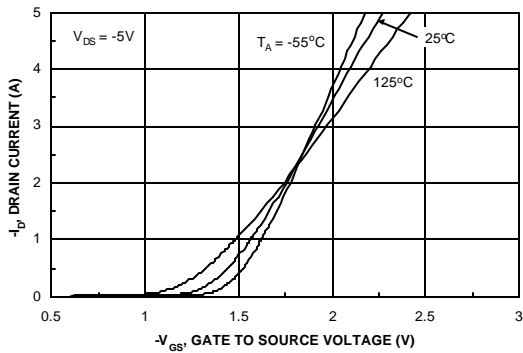


Figure 5. Transfer Characteristics.

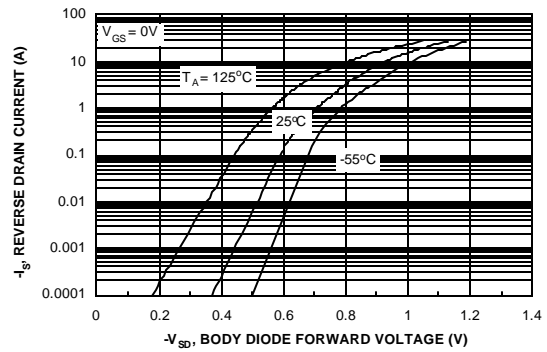


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Characteristics

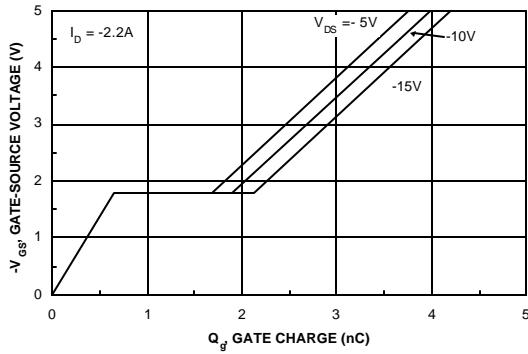


Figure 7. Gate Charge Characteristics.

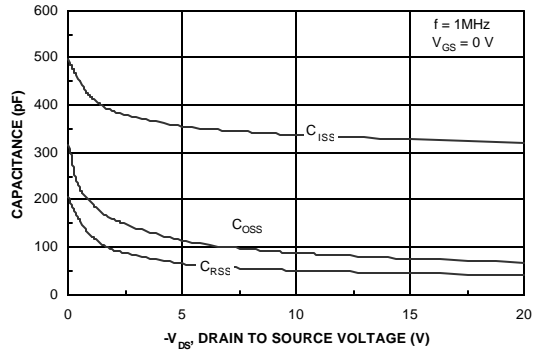


Figure 8. Capacitance Characteristics.

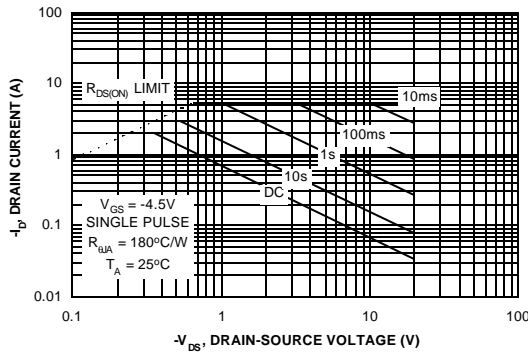


Figure 9. Maximum Safe Operating Area.

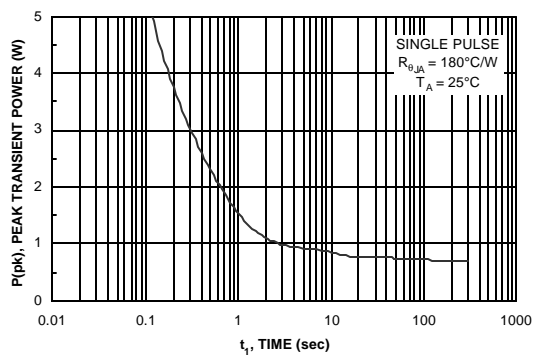


Figure 10. Single Pulse Maximum Power Dissipation.

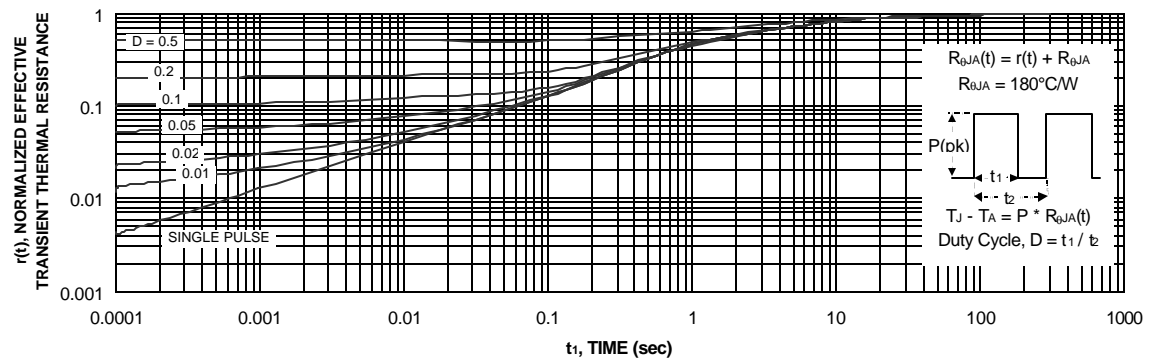


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.  
Transient thermal response will change depending on the circuit board design.

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